imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





DATASHEET

Description

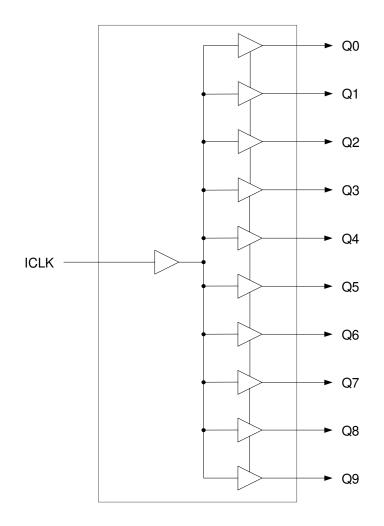
The 74FCT3807S is a low skew, single input to ten output, clock buffer. The 74FCT3807S has best in class additive phase Jitter of sub 50 fsec.

IDT makes many non-PLL and PLL based low skew output devices as well as Zero Delay Buffers to synchronize clocks. Contact us for all of your clocking needs.

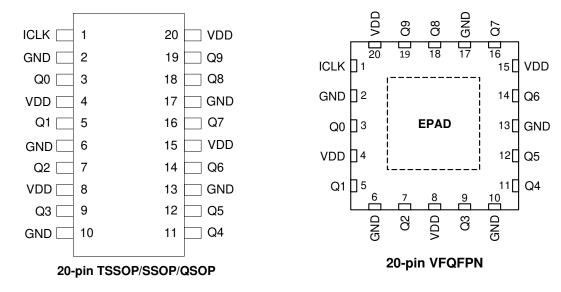
Features

- · Low additive phase jitter RMS: 50fs
- · Low skew outputs (50ps)
- Packaged in 20-pin TSSOP, SSOP, QSOP and VFQFPN packages, Pb (lead) free
- Operating voltages of 1.8V to 3.3V
- · Input/Output clock frequency up to 200 MHz
- Advanced, low power CMOS process
- Extended temperature range (-40°C to +105°C)

Block Diagram



Pin Assignments



Pin Descriptions

Pin Number	Pin Name	Pin Type	Pin Description
1	ICLK	Input	Clock input.
2	GND	Power	Connect to ground.
3	Q0	Output	Clock output 0.
4	VDD	Power	Connect to +1.8V, +2.5 V, or +3.3 V.
5	Q1	Output	Clock output 1.
6	GND	Power	Connect to ground.
7	Q2	Output	Clock Output 2.
8	VDD	Power	Connect to +1.8V, +2.5 V, or +3.3 V.
9	Q3	Output	Clock Output 3.
10	GND	Power	Connect to ground.
11	Q4	Output	Clock Output 4.
12	Q5	Output	Clock Output 5.
13	GND	Power	Connect to ground.
14	Q6	Output	Clock Output 6.
15	VDD	Power	Connect to +1.8V, +2.5 V, or +3.3 V.
16	Q7	Output	Clock Output 7.
17	GND	Power	Connect to ground.
18	Q8	Output	Clock Output 8.
19	Q9	Output	Clock Output 9.
20	VDD	Power	Connect to +1.8V, +2.5 V, or +3.3 V.

External Components

A minimum number of external components are required for proper operation. A decoupling capacitor of 0.01μ F should be connected between VDD pins and GND pins, as close to the device as possible. A 33Ω series terminating resistor may be used on each clock output if the trace is longer than 1 inch.

To achieve the low output skew that the 74FCT3807S is capable of, careful attention must be paid to board layout. Essentially, all ten outputs must have identical terminations, identical loads and identical trace geometries. If they do not, the output skew will be degraded. For example, using a 30Ω series termination on one output (with 33Ω on the others) will cause at least 15 ps of skew.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 74FCT3807S. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	3.465V
Outputs	-0.5 V to VDD+0.5 V
ICLK	3.465V
Ambient Operating Temperature (extended)	-40° to +105°C
Storage Temperature	-65° to +150°C
Junction Temperature	125°C
Soldering Temperature	260°C

Recommended Operation Conditions

Parameter	Min.	Тур.	Max.	Units
Ambient Operating Temperature (extended)	-40		+105	°C
Power Supply Voltage (measured in respect to GND)	+1.71		+3.465	V

DC Electrical Characteristics

(VDD = 1.8V, 2.5V, 3.3V)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		1.71		1.89	V
Input High Voltage, ICLK	V _{IH}	Note 1	0.7xVDD		VDD	V
Input Low Voltage, ICLK	V _{IL}	Note 1			0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -10 mA	1.3			V
Output Low Voltage	V _{OL}	I _{OL} = 10 mA			0.35	V
Operating Supply Current	IDD	No load, 135 MHz		35		mA
Nominal Output Impedance	Z _O			17		Ω
Input Capacitance	C _{IN}	ICLK		5		pF

VDD=1.8V ±5%, Ambient temperature -40° to +105°C, unless stated otherwise

Notes: 1. Nominal switching threshold is VDD/2

VDD=2.5 V ±5%, Ambient temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		2.375		2.625	V
Input High Voltage, ICLK	V _{IH}	Note 1	0.7xVDD		VDD	V
Input Low Voltage, ICLK	VIL	Note 1			0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -16 mA	1.8			V
Output Low Voltage	V _{OL}	I _{OL} = 16 mA			0.5	V
Operating Supply Current	IDD	No load, 135 MHz		45		mA
Nominal Output Impedance	Z _O			17		Ω
Input Capacitance	C _{IN}	ICLK		5		pF

VDD=3.3 V \pm 5% , Ambient temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		3.15		3.45	V
Input High Voltage, ICLK	V _{IH}	Note 1	0.7xVDD		VDD	V
Input Low Voltage, ICLK	V _{IL}	Note 1			0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -25 mA	2.2			V
Output Low Voltage	V _{OL}	I _{OL} = 25 mA			0.7	V
Operating Supply Current	IDD	No load, 135 MHz		55		mA
Nominal Output Impedance	Z _O			17		Ω
Input Capacitance	C _{IN}	ICLK		5		pF

AC Electrical Characteristics

(VDD = 1.8V, 2.5V, 3.3V)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.36 to 1.44 V, C _L =5 pF		1.4	1.9	ns
Output Fall Time	t _{OF}	1.44 to 0.36 V, C _L =5 pF		1.4	1.9	ns
Propagation Delay		Note 1	1.5	2.5	4	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew		Rising edges at VDD/2, Note 2		50	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps
Start-up Time	t _{START-UP}	Part start-up time for valid outputs after VDD ramp-up			2	ms

VDD = 2.5 V ±5%, Ambient Temperature -40° to -	+105°C, unless stated otherwise
--	---------------------------------

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.5 to 2.0 V, C _L =5 pF		1.0	1.5	ns
Output Fall Time	t _{OF}	2.0 to 0.5 V, C _L =5 pF		1.0	1.5	ns
Propagation Delay		Note 1	1.8	2.5	4.5	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew		Rising edges at VDD/2, Note 2		50	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps
Start-up Time	t _{START-UP}	Part start-up time for valid outputs after VDD ramp-up			2	ms

VDD = 3.3 V ±5%, Ambient Temperature -40° to +105°C, unless stated otherwise

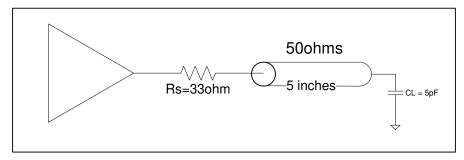
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.66 to 2.64 V, C _L =5 pF		0.6	1.0	ns
Output Fall Time	t _{OF}	2.64 to 0.66 V, C _L =5 pF		0.6	1.0	ns
Propagation Delay		Note 1	1.5	2.5	4	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew		Rising edges at VDD/2, Note 2		50	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps
Start-up Time	t _{START-UP}	Part start-up time for valid outputs after VDD ramp-up			2	ms

Notes:

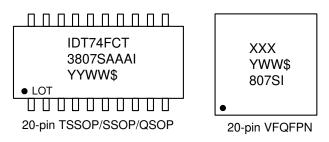
1. With rail to rail input clock

Between any 2 outputs with equal loading.
 Duty cycle on outputs will match incoming clock duty cycle. Consult IDT for tight duty cycle clock generators.

Test Load and Circuit

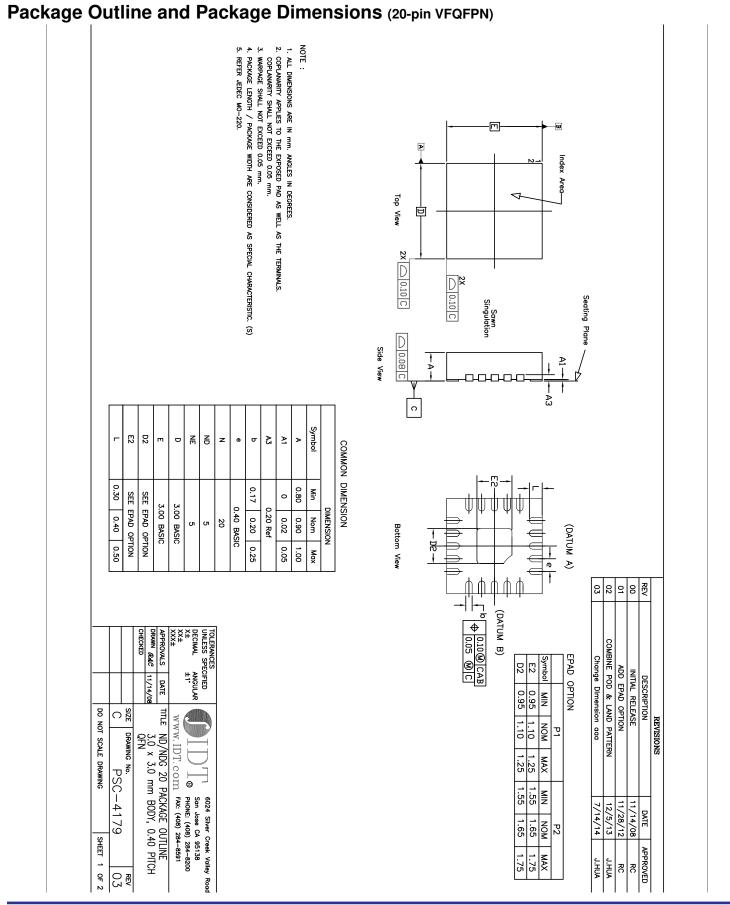


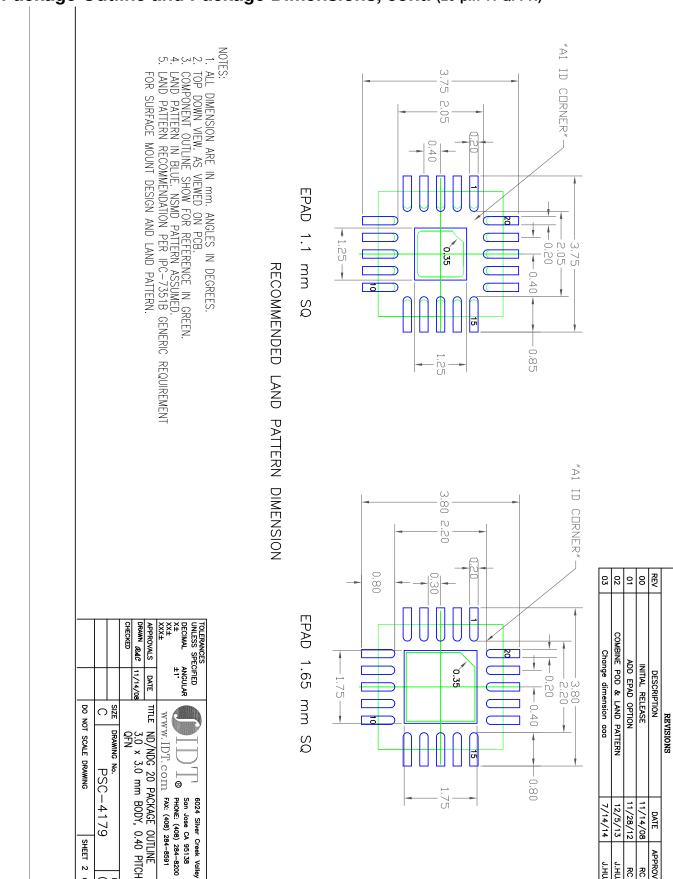
Marking Diagrams



Notes:

- 1. "LOT" denotes the lot number.
- 2. "XXX" denotes the lot number.
- 3. "YYWW" or "YWW" are the last digits of the year and week that the part was assembled.
- 4. "\$" denotes mark code.
- 5. "I" denotes extended temperature range device.
- 6. "AAA" denotes package code.





Package Outline and Package Dimensions, cont. (20-pin VFQFPN)

SHEET 2 OF 2

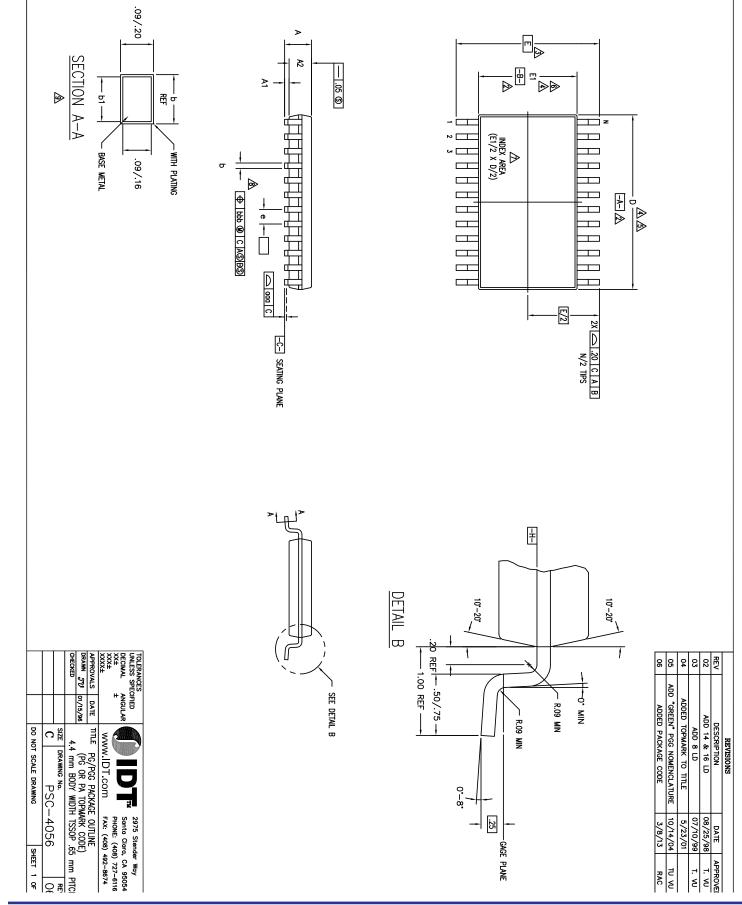
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Package Outline and Package Dimensions (20-pin TSSOP)



mm 2975 Stender Way Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674

SHEET 2 OF 3

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	=	10	Ø	⊗	\land	♪	A	A	A		<u> </u>		
	THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION AA, AB-1, AB, AC, AD & AE	ALL DIMENSIONS ARE IN MILLIMETERS	THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP	LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT	detail of Pin 1 identifier is optional but must be located within The zone indicated	DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE	DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE	DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE -H-	DIMENSION E TO BE DETERMINED AT SEATING PLANE $[-C-]$	datums [_a_] and [_b_] to be determined at datum plane [_h_]	ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994	NOTES:	
		APPROVALS DATE III-E PG/PGG PACKAGE OUTLINE OREOXED 4.4 mm BODY WIDTH TSSOP 65 mm	ANGULAR ↓ WWW.IDT.com	INLESS SPECIFIED									

Pa 20-pin TSSOP)

	90	05	04	03	02	REV		
	ADDED PACKAGE CODE	ADD "GREEN" PGG NOMENCLATURE	ADDED TOPMARK TO TITLE	ADD 8 LD	ADD 14 & 16 LD	DESCRIPTION	REVISIONS	
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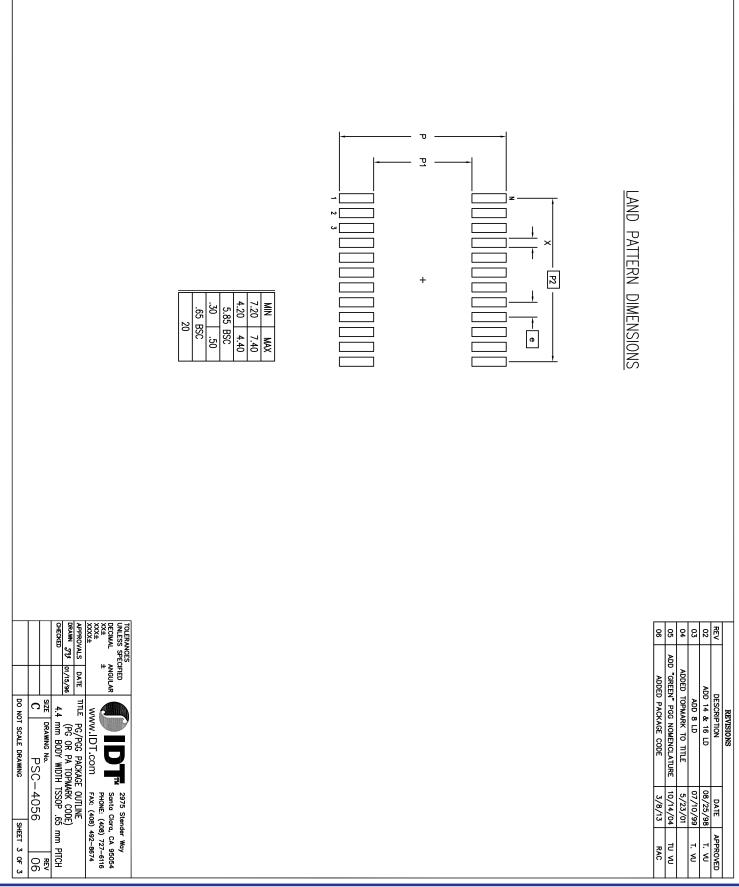
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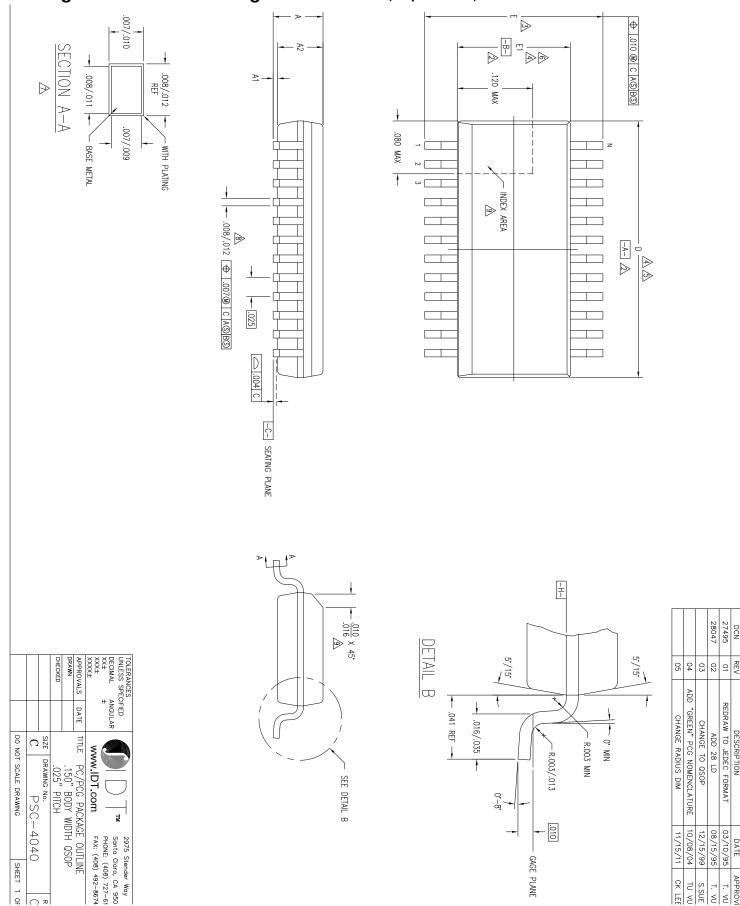
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PG/PGG20

Package Outline and Package Dimensions, cont. (20-pin TSSOP)



Package Outline and Package Dimensions (20-pin QSOP)



REVISIONS

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Package Outline and Package Dimensions, cont. (20-pin QSOP)

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VARIATION AB, AD, AE & AF. EXCEPTIONS: JEDEC DIMENSION AZ MAX IS .059	THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-137,	ALL DIMENSIONS ARE IN INCHES	THE CHAMFER ON THE PACKAGE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE ZONE INDICATED	LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE DAMBAR PROTRUSION IS .004 IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT	THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 FROM LEAD TIP	DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 PER SIDE	DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 PER SIDE	DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE -H-	DIMENSION E TO BE DETERMINED AT SEATING PLANE -C-	DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-	ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982	NOTES:	JEDEC VARIATION N AD T T .061 .064 .068 .004 .006 .010 .337 .342 .344 4.5 .150 .155 .157 4.6 20 20 4.6 4.6
DO NOT SCALE DRAWING	ACKA	XX± WWW.IDT.com FAX: (408) 492-8674		20 8	.142 .150 .225 BSC 010 018	MIN MAX .274 .282	-					+	AND PATTERN DIMENSIONS

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 ADD 28 LD
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 CHANGE TO QSOP
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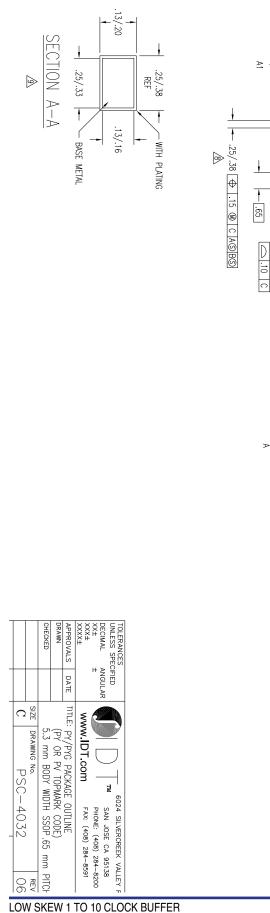
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 ADD "GREIN" PGC NOMENCLATURE
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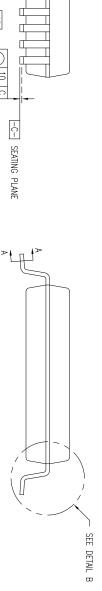
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 CHANGE RADIUS DIM
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 CK LEE

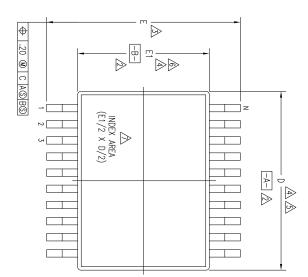
Package Outline and Package Dimensions (20-pin SSOP)

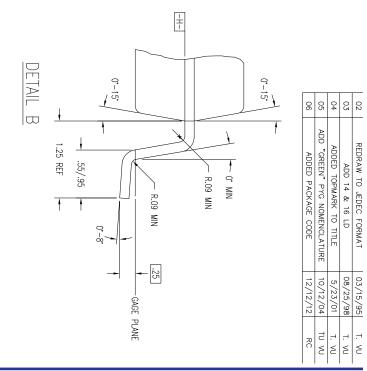
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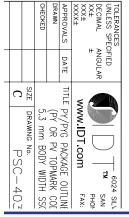


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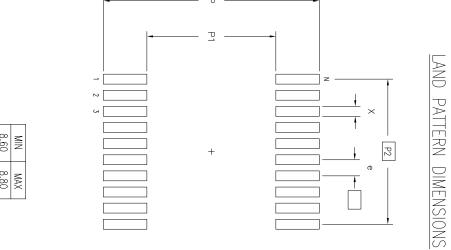
Package Outline and Package Dimensions, cont. (20-pin SSOP)

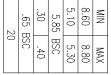
	5.20	7.65	7.07	1.68	.05	1.73	MIN		JEDEC	
20	5.30	7.80	7.20	1.73	.13	1.86	NON	AE	VARIATION	PY/PYG20
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Package Outline and Package Dimensions, cont. (20-pin SSOP)





6	05 /	04	03	02	9	8	REV	
ADDED PACKAGE CODE	ADD "GREEN" PYG NOMENCLATURE	ADDED TOPMARK TO TITLE	ADD 14 & 16 LD	REDRAW TO JEDEC FORMAT	ADD 28 LD	INITIAL RELEASE	DESCRIPTION	A 4444 • A 444 A 44 A 144
12/12/12	10/12/04	5/23/01	08/25/98	03/15/95	07/27/93	04/15/91	DATE	
RC	TU VU	T. VU	T. VU	T. VU	T. VU	T. VU	APPROVED	







Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
74FCT3807SNDGI	see page 6	Tubes	20-pin VFQFPN	-40° to +105°C
74FCT3807SNDGI8		Tape and Reel	20-pin VFQFPN	-40° to +105°C
74FCT3807SPGGI		Tubes	20-pin TSSOP	-40° to +105°C
74FCT3807SPGGI8		Tape and Reel	20-pin TSSOP	-40° to +105°C
74FCT3807SQGI		Tubes	20-pin QSOP	-40° to +105°C
74FCT3807SQGI8		Tape and Reel	20-pin QSOP	-40° to +105°C
74FCT3807SPYGI		Tubes	20-pin SSOP	-40° to +105°C
74FCT3807SPYGI8		Tape and Reel	20-pin SSOP	-40° to +105°C

"G" after the two-letter package code denotes Pb-Free configuration, RoHS compliant.

Revision History

Rev.	Date	Originator	Description of Change
А	03/18/15	B. Chandhoke	Initial release.



Corporate Headquarters 6024 Silver Creek Valley Road San Jose, CA 95138 USA

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